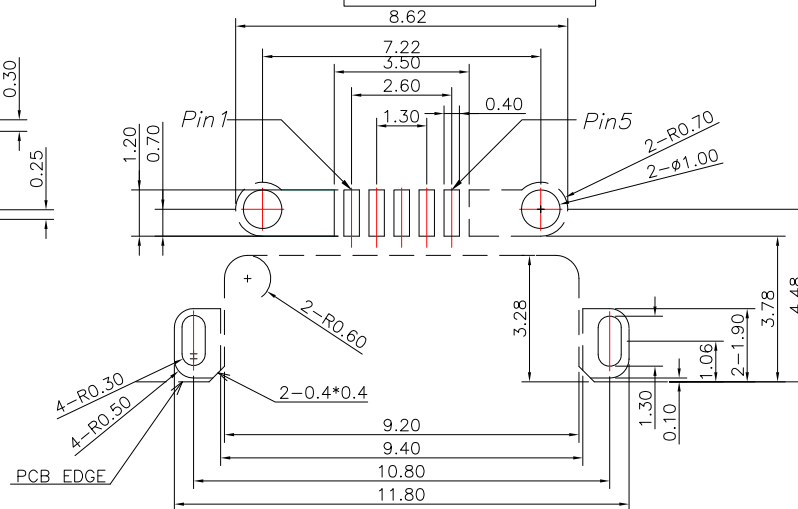
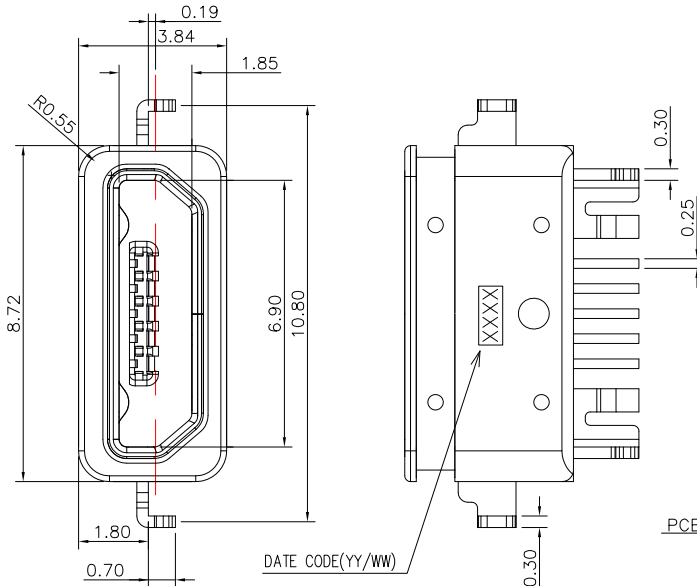
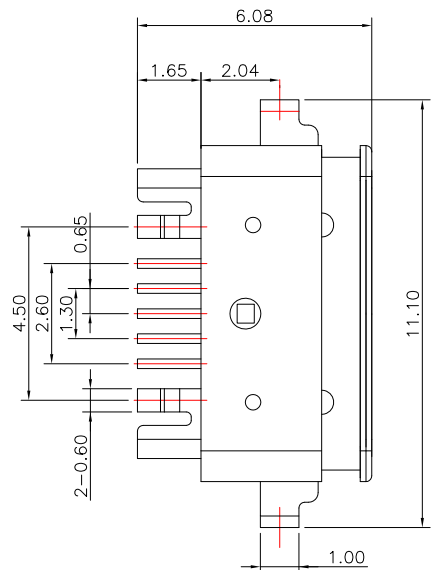
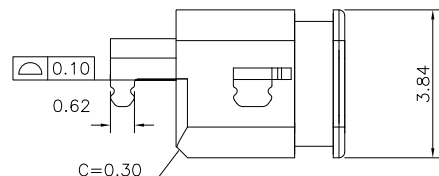


# IP67



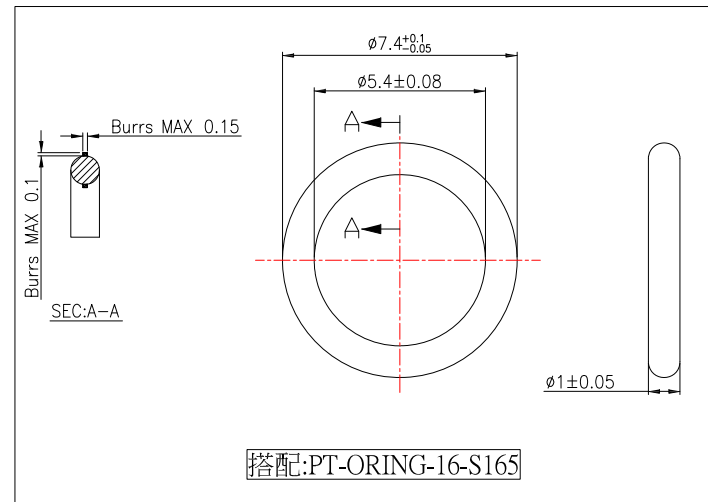
P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP13-x-S165

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



搭配:PT-ORING-16-S165

NOTES:

MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: SUS
- 1.4 O-RING: SILICON

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;  
GOLD PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

- 3.1 RATING: 1.0A
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 500 VAC
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

5	新增O-RING圖	Jack	102920
5	刪除O-RING圖	Jack	040819
4	更新樣式	Jack	032119
3	新增O-RING圖	Jack	112618
2	新增尺寸	Jack	073118
1	更新為A0版	Jack	071718
ITEM NO.	DESCRIPTION	DRAWN	DATE

東莞市高迪電子有限公司  
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED:	Up to 5 ±0.2	Above 5 ~ 15 ±0.3	Above 15 ~ 30 ±0.4	Above 30 ~ 50 ±0.5	Angle ±0.3°
	3RD. ANGEL'S	UNITS	MM		

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	10/29/20			
CHECKED BY:	DATE	FINISH	MODLE	MICRO USB 5PF B TYPE 沉板上 H 1.8 IP67
Jacky Chen	10/29/20			
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-WP13-x-S165
Tony Kao	10/29/20	1 : 1		
		SHEET NO.	PART NO.	MRUSB-5B-WP13-x-S165
		1 of 1		
				SIZE: A4
				VER: R6